



BUK9213-30A

N-channel TrenchMOS logic level FET

Rev. 02 — 18 February 2011

Product data sheet

1. Product profile

1.1 General description

Logic level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features and benefits

- AEC Q101 compliant
- Suitable for logic level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

1.3 Applications

- 12 V loads
- Automotive and general purpose power switching
- Motors, lamps and solenoids

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25\text{ °C}$; $T_j \leq 175\text{ °C}$	-	-	30	V
I_D	drain current	$V_{GS} = 5\text{ V}$; $T_{mb} = 25\text{ °C}$; see Figure 1 ; see Figure 3	1	-	75	A
P_{tot}	total power dissipation	$T_{mb} = 25\text{ °C}$; see Figure 2	-	-	150	W
Static characteristics						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$; $I_D = 25\text{ A}$; $T_j = 25\text{ °C}$	-	9	11	mΩ
		$V_{GS} = 4.5\text{ V}$; $I_D = 25\text{ A}$; $T_j = 25\text{ °C}$	-	-	14.4	mΩ
		$V_{GS} = 5\text{ V}$; $I_D = 25\text{ A}$; $T_j = 25\text{ °C}$; see Figure 11 ; see Figure 12	-	11	13	mΩ



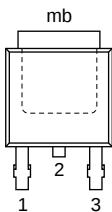
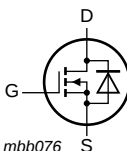
Table 1. Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 55\text{ A}$; $V_{sup} \leq 30\text{ V}$; $R_{GS} = 50\ \Omega$; $V_{GS} = 5\text{ V}$; $T_{J(init)} = 25\text{ }^\circ\text{C}$; unclamped	-	-	467	mJ
Dynamic characteristics						
Q_{GD}	gate-drain charge	$V_{GS} = 5\text{ V}$; $I_D = 25\text{ A}$; $V_{DS} = 24\text{ V}$; $T_J = 25\text{ }^\circ\text{C}$; see Figure 13	-	18	-	nC

[1] Current is limited by power dissipation chip rating.

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	D	drain		
3	S	source		
mb	D	mounting base; connected to drain		

SOT428 (DPAK)

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK9213-30A	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage	T _j ≥ 25 °C; T _j ≤ 175 °C	-	30	V
V _{DGR}	drain-gate voltage	R _{GS} = 20 kΩ	-	30	V
V _{GS}	gate-source voltage		-15	15	V
I _D	drain current	T _{mb} = 100 °C; V _{GS} = 5 V; see Figure 1	[1] -	54	A
		T _{mb} = 25 °C; V _{GS} = 5 V; see Figure 1 ; see Figure 3	[1] -	75	A
			[2] -	55	A
I _{DM}	peak drain current	T _{mb} = 25 °C; pulsed; t _p ≤ 10 μs; see Figure 3	-	311	A
P _{tot}	total power dissipation	T _{mb} = 25 °C; see Figure 2	-	150	W
T _{stg}	storage temperature		-55	175	°C
T _j	junction temperature		-55	175	°C
Source-drain diode					
I _S	source current	T _{mb} = 25 °C	[1] -	75	A
			[2] -	55	A
I _{SM}	peak source current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C	-	311	A
Avalanche ruggedness					
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	I _D = 55 A; V _{sup} ≤ 30 V; R _{GS} = 50 Ω; V _{GS} = 5 V; T _{j(init)} = 25 °C; unclamped	-	467	mJ

[1] Current is limited by power dissipation chip rating.

[2] Continuous current is limited by bondwires.

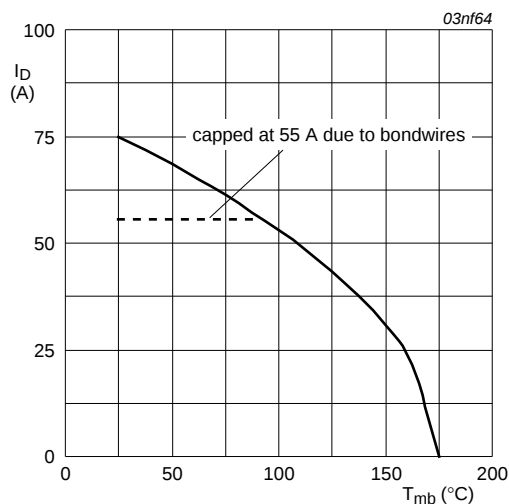


Fig. 1. Continuous drain current as a function of mounting base temperature

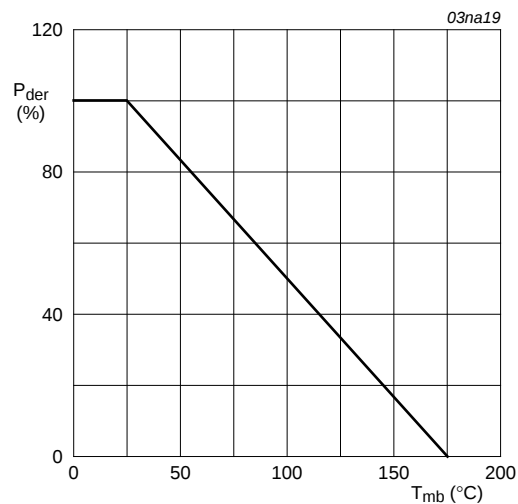


Fig. 2. Normalized total power dissipation as a function of mounting base temperature

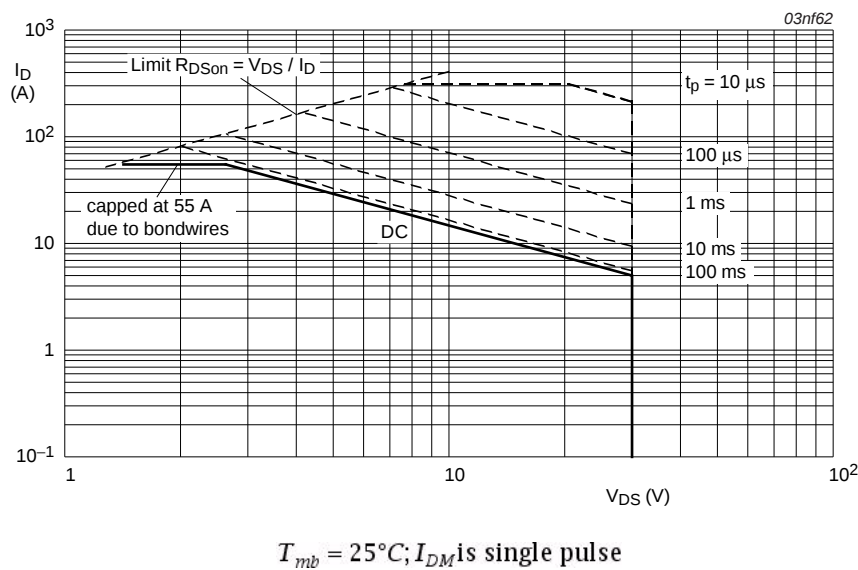


Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 4	-	0.56	1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient		-	71.4	-	K/W

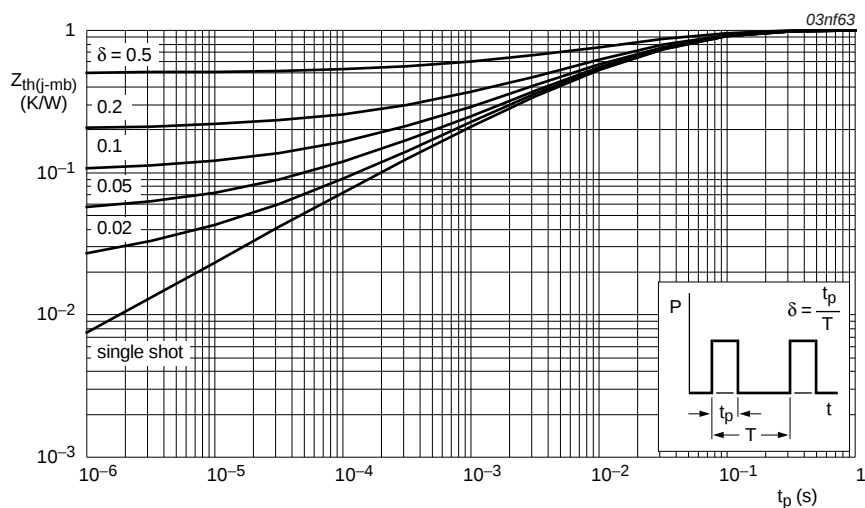


Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V _{(BR)DSS}	drain-source breakdown voltage	I _D = 0.25 mA; V _{GS} = 0 V; T _J = 25 °C	30	-	-	V
		I _D = 0.25 mA; V _{GS} = 0 V; T _J = -55 °C	27	-	-	V
V _{GS(th)}	gate-source threshold voltage	I _D = 1 mA; V _{DS} = V _{GS} ; T _J = -55 °C; see Figure 10	-	-	2.3	V
		I _D = 1 mA; V _{DS} = V _{GS} ; T _J = 175 °C; see Figure 10	0.5	-	-	V
		I _D = 1 mA; V _{DS} = V _{GS} ; T _J = 25 °C; see Figure 10	1	1.5	2	V
I _{DSS}	drain leakage current	V _{DS} = 30 V; V _{GS} = 0 V; T _J = 175 °C	-	-	500	μA
		V _{DS} = 30 V; V _{GS} = 0 V; T _J = 25 °C	-	0.05	10	μA
I _{GSS}	gate leakage current	V _{GS} = 10 V; V _{DS} = 0 V; T _J = 25 °C	-	2	100	nA
		V _{GS} = -10 V; V _{DS} = 0 V; T _J = 25 °C	-	2	100	nA
R _{DSon}	drain-source on-state resistance	V _{GS} = 10 V; I _D = 25 A; T _J = 25 °C	-	9	11	mΩ
		V _{GS} = 5 V; I _D = 25 A; T _J = 175 °C; see Figure 11 ; see Figure 12	-	-	24	mΩ
		V _{GS} = 4.5 V; I _D = 25 A; T _J = 25 °C	-	-	14.4	mΩ
		V _{GS} = 5 V; I _D = 25 A; T _J = 25 °C; see Figure 11 ; see Figure 12	-	11	13	mΩ
Dynamic characteristics						
Q _{G(tot)}	total gate charge	I _D = 25 A; V _{DS} = 24 V; V _{GS} = 5 V; T _J = 25 °C; see Figure 13	-	37	-	nC
Q _{GS}	gate-source charge		-	7	-	nC
Q _{GD}	gate-drain charge	I _D = 25 A; V _{DS} = 24 V; V _{GS} = 5 V; T _J = 25 °C; see Figure 13	-	18	-	nC
C _{iss}	input capacitance	V _{GS} = 0 V; V _{DS} = 25 V; f = 1 MHz; T _J = 25 °C; see Figure 14	-	2140	2852	pF
C _{oss}	output capacitance		-	550	660	pF
C _{rss}	reverse transfer capacitance		-	334	457	pF
t _{d(on)}	turn-on delay time	V _{DS} = 20 V; R _L = 2.7 Ω; V _{GS} = 5 V; R _{G(ext)} = 10 Ω; T _J = 25 °C	-	26	-	ns
t _r	rise time		-	202	-	ns
t _{d(off)}	turn-off delay time	V _{DS} = 20 V; R _L = 2.7 Ω; V _{GS} = 5 V; R _{G(ext)} = 10 Ω; T _J = 25 °C	-	134	-	ns
t _f	fall time	V _{DS} = 20 V; R _L = 2.7 Ω; V _{GS} = 5 V; R _{G(ext)} = 10 Ω; T _J = 25 °C	-	158	-	ns
L _D	internal drain inductance	measured from drain to centre of die; T _J = 25 °C	-	2.5	-	nH
L _S	internal source inductance	measured from source lead to source bond pad; T _J = 25 °C	-	7.5	-	nH

Table 6. Characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Source-drain diode						
V_{SD}	source-drain voltage	$I_S = 15\text{ A}$; $V_{GS} = 0\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$; see Figure 15	-	0.85	1.2	V
t_{rr}	reverse recovery time	$I_S = 20\text{ A}$; $dI_S/dt = -100\text{ A}/\mu\text{s}$;	-	55	-	ns
Q_r	recovered charge	$V_{GS} = -10\text{ V}$; $V_{DS} = 20\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$	-	24	-	nC

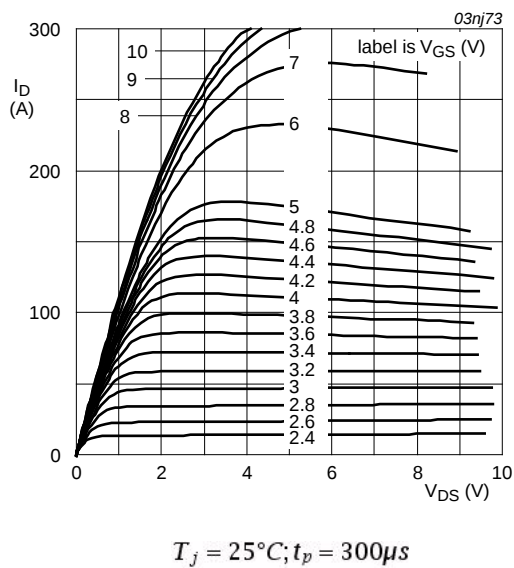


Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values

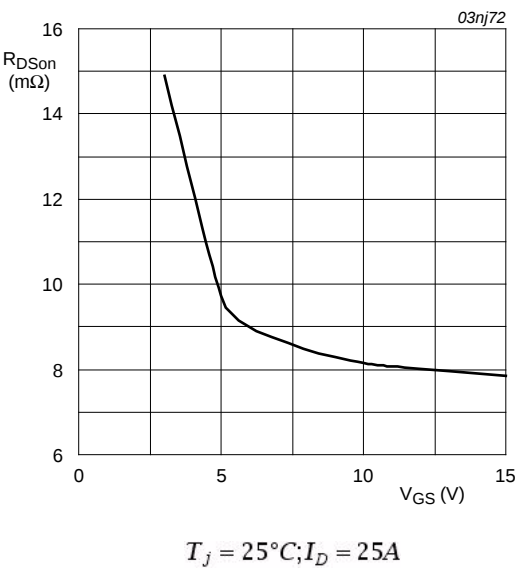


Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values

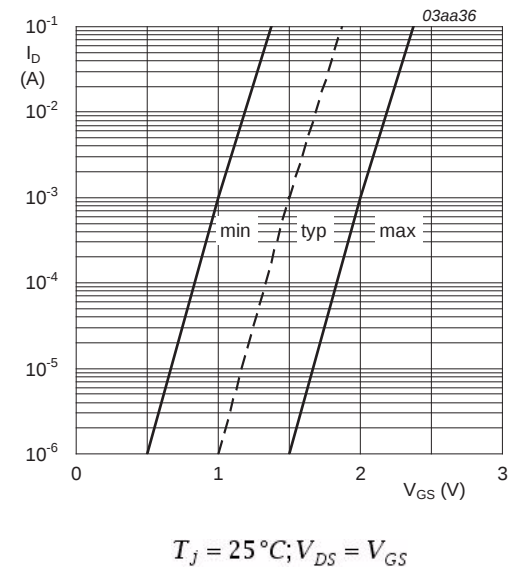


Fig 7. Sub-threshold drain current as a function of gate-source voltage

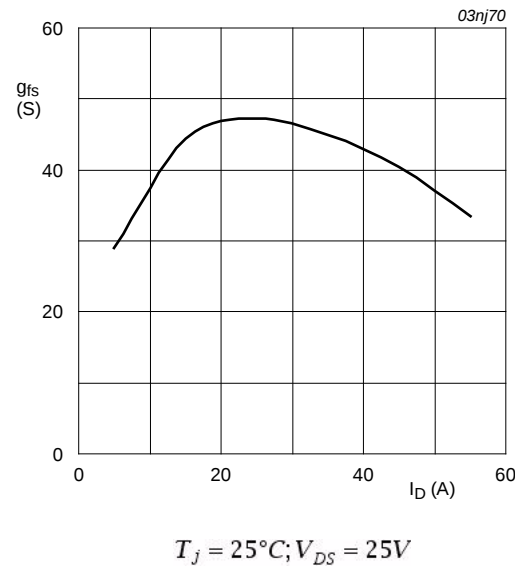


Fig 8. Forward transconductance as a function of drain current; typical values

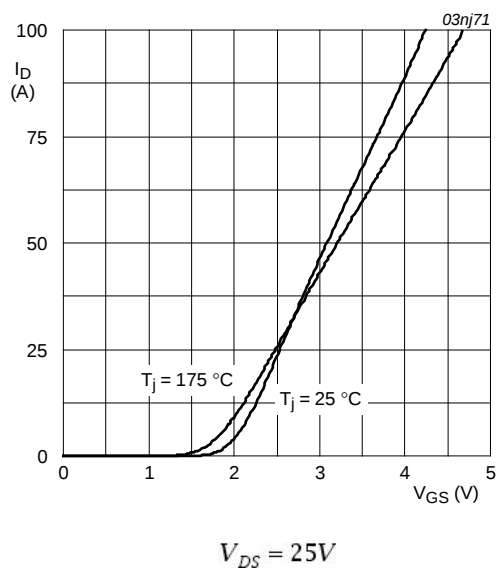


Fig 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

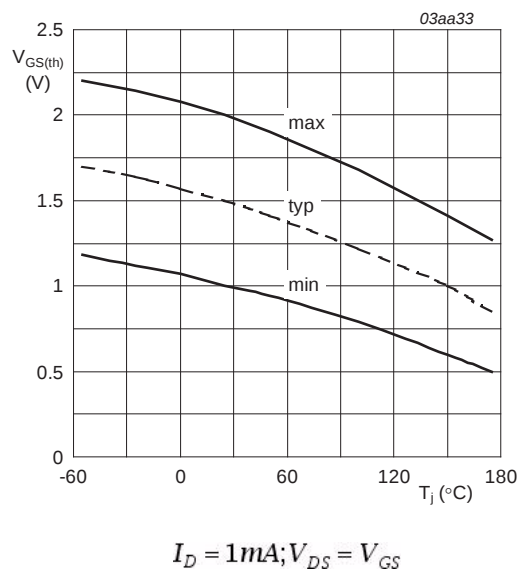


Fig 10. Gate-source threshold voltage as a function of junction temperature

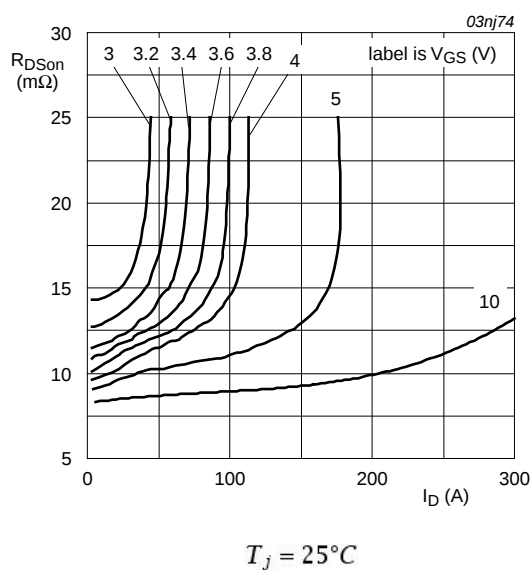


Fig 11. Drain-source on-state resistance as a function of drain current; typical values

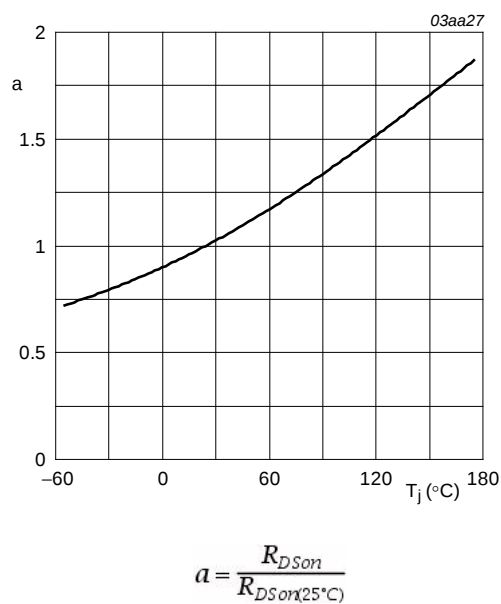
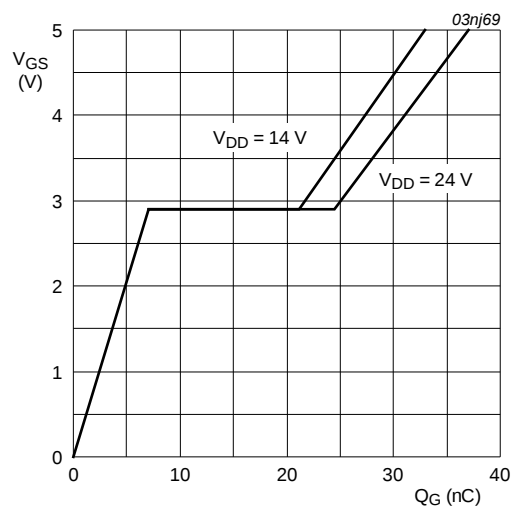
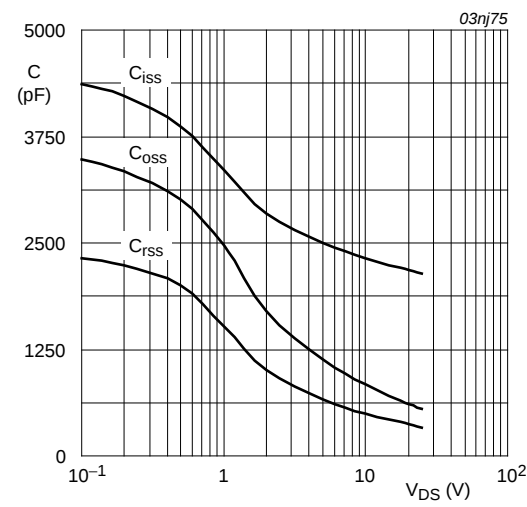


Fig 12. Normalized drain-source on-state resistance factor as a function of junction temperature



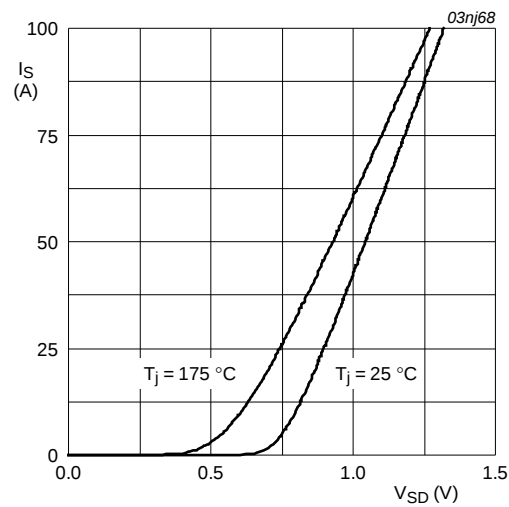
$T_j = 25^\circ\text{C}; I_D = 25\text{ A}$

Fig 13. Gate-source voltage as a function of turn-on gate charge; typical values



$V_{GS} = 0\text{ V}; f = 1\text{ MHz}$

Fig 14. Input and reverse transfer capacitances as a function of drain-source voltage; typical values



$V_{GS} = 0\text{ V}$

Fig 15. Reverse diode current as a function of reverse diode voltage; typical values

7. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)

SOT428

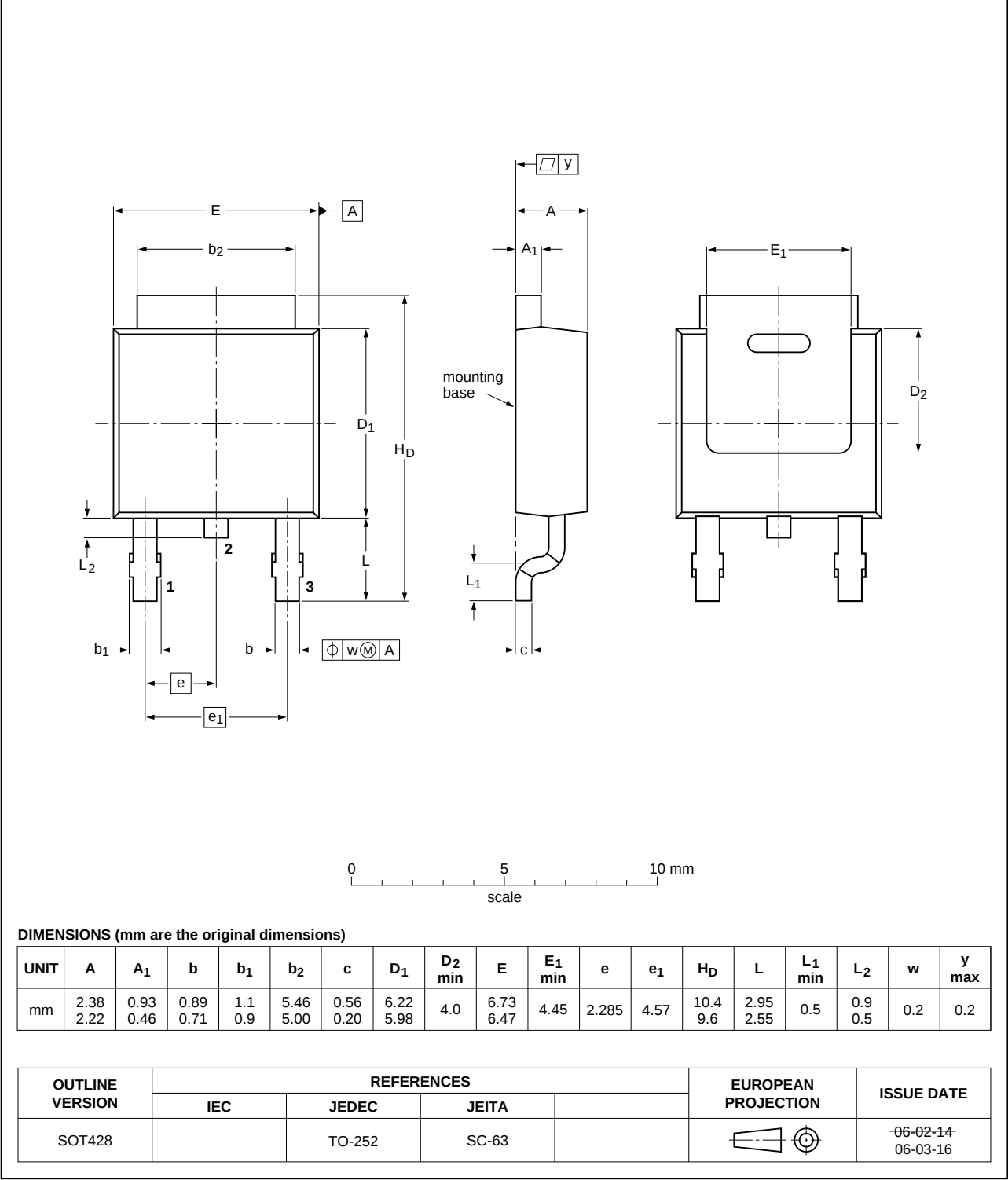


Fig 16. Package outline SOT428 (DPAK)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BUK9213-30A v.2	20110218	Product data sheet	-	BUK9213-30A v.1
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Various changes to content.			
BUK9213-30A v.1	20020729	Product data	-	-

9. Legal information

9.1 Data sheet status

Document status ^{[1] [2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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